

Printed Electronics Forum- powered by OE-A and LOPEC, Nov. 13/14



Flexible and Printed Electronics: Applications & Technologies

Date Wednesday, November 13, 2024
Time 14:00 – 17:10 h
Venue Printed Electronics Forum, PCB and EMS Marketplace, Hall A1
Moderation Dr. Klaus Hecker, Managing Director, OE-A

- 14:00 h Introduction to Flexible and Printed Electronics
Dr. Klaus Hecker, Managing Director, OE-A (DE)
- 14:05 h Printed E-Paper Display: Innovation and Applications Revolutionizing Display Technology
Dr. Carlos Pinheiro, CTO, Ynvisible (CA)
- 14:25 h Printed electronics in customised production: a case study in elderly care
Dr. Philip Renners, Vice President of Research & Development, Witte Technology (DE)
- 14:45 h Smart Hard Hat for Workers Safety Monitoring and Environmental Evaluation
José Matos, Team Leader Smart Systems, Centi
- 15:05 h Thermal Laser Processes in Printed Electronics - sustainable and rapid post-processing for high volume production
Alexander Görk, Business Development Manager Industrial Components, Hamamatsu Photonics Deutschland (DE)
- 15:25 h Advancing Printed Electronics from Concepts to Upscaled Manufacturing using a Pilot Factory
Antti Kemppainen, Key Account Manager, VTT (FI)
- 15:45 h Sustainable hybrid printed electronics allowing resilient method
Dr. David Nilsson, Business Developer Printed Electronics, RISE (SE)
- 16:05 h Copper inks: Lower cost and sustainable alternative for printing PCBs, antennas and PV cells
Dr. Ofer Shochet, CEO, Copprint (IL)
- 16:25 h Cut n' paste atomics: a new paradigm in graphene integration into flexible electronics
Abhay Shivayogimath, Founder, CEO, 2D ApS (DK)
- 16:45 h Low-Cost Copper Ink Enabling Mass Volume Printed Electronics Manufacturing
Steve Paschky, Co-founder, Sales & Marketing Director, Saralon (DE)
- 17:05 h Summary & Adjourn
Dr. Klaus Hecker, Managing Director, OE-A (DE)

A working group within

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Flexible and Printed Electronics for Automotive Applications

Date Thursday, November 14, 2024
 Time 14:00 - 17:10 h
 Venue Printed Electronics Forum, Smart Mobility Stage, Hall B6

Moderation Raswanth Sendhil Sasikala, Project Manager, OE-A

- 14:00 h Introduction to Flexible and Printed Electronics
Raswanth Sendhil Sasikala, Project Manager, OE-A
- 14:05 h Integrated automotive HMI surfaces with decoration, touch, light
Dr. Wolfgang Clemens, Director Product Management & Business Development, PolyIC (DE)
- 14:25 h IMSE is Shaping the Future of Automotive Design, Performance and Sustainability
Dr. Dominique Heilborn, Director Automotive, Tactotek (FI)
- 14:45 h Printed piezoelectric sensing solutions for automotive applications
Declan Flannery, VP Operations & Manufacturing, Interlink Electronics Inc. (US)
- 15:05 h Digital Processes for 3D Circuit Carriers
Dr. Wolfgang Eberhardt, Head of Technology, Hahn-Schickard (DE)
- 15:25 h Process and cost-efficient automotive monitoring solutions
Dominik Reukauf, Technical Business Development Manager, Lohmann (DE)
- 15:45 h Reliability Improvements for Automotive Applications using AI and Quality Management
Wolfgang Mildner, tba, BayflexSolutions (US)
- 16:05 h Printed Electronics: How conductive inks enable new opportunities to future automotive efficiency
Aad van der Spuij, Business Development Manager EIMEA, Henkel (BE)
- 16:25 h Elevating Precision and Resolution in Automotive Printed Electronics with HPCaP Technology
Sahar Al Kamand, Sales Engineer, Hummink (FR)
- 16:45 h Customized & Scalable Printed Electronics Solutions for Automotive
Dr. Florian Ullrich, Head of Business Development, Flexoo (DE)
- 17:05 h Summary & Adjourn
Raswanth Sendhil Sasikala, Project Manager, OE-A